



## Material Content Data Sheet



Halogen-Free

<b>Sales Product Name</b>	IPD122N10N3 G	<b>Issued</b>	11. May 2021
<b>MA#</b>	MA001662902		
<b>Package</b>	PG-TO252-3-313	<b>Weight*</b>	320.25 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.094	0.97	0.97	9660	9660
leadframe	inorganic material	phosphorus	7723-14-0	0.044	0.01		138	
	non noble metal	iron	7439-89-6	0.147	0.05		460	
	non noble metal	copper	7440-50-8	147.096	45.94	46.00	459321	459919
wire	non noble metal	aluminium	7429-90-5	5.169	1.61	1.61	16141	16141
encapsulation	inorganic material	zinc oxide	1314-13-2	1.374	0.43		4290	
	miscellaneous	miscellaneous	-	6.869	2.14		21449	
	plastics	epoxy resin	-	20.607	6.43		64348	
	inorganic material	silicon dioxide	60676-86-0	108.532	33.89	42.89	338901	428988
lead finish	non noble metal	tin	7440-31-5	3.740	1.17	1.17	11679	11679
plating	inorganic material	phosphorus	7723-14-0	0.003			11	
	non noble metal	nickel	7440-02-0	1.421	0.44	0.44	4436	4447
solder	non noble metal	tin	7440-31-5	0.059	0.02		184	
	noble metal	silver	7440-22-4	0.074	0.02		230	
	non noble metal	lead	7439-92-1	2.815	0.88	0.92	8791	9205
heatspreader	inorganic material	phosphorus	7723-14-0	0.006			18	
	non noble metal	iron	7439-89-6	0.019	0.01		60	
	non noble metal	copper	7440-50-8	19.177	5.99	6.00	59883	59961
*deviation	< 10%	Sum in total:				100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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